

Gold process installed in our factory

ENIG-process in-house in our Swedish factory – decreasing lead time!

We worked hard during autumn 2018 with installation and optimizing of our new investment in a brand new ENIG-process. ENIG (Electroless Nickel Immersion Gold) is a well proven final finish that allows several soldering cycles with an even surface. Tin HASL is still the most common surface treatment, however gold continue to increase in use due to smaller pads.



The ENIG-line is 7 meter long and consists of more than 20 different chemical baths, heaters, pumps and vibrator systems.



Per-Olof Javermark and Håkan Rask hoists the first panel with Gold in our new ENIG-process line.

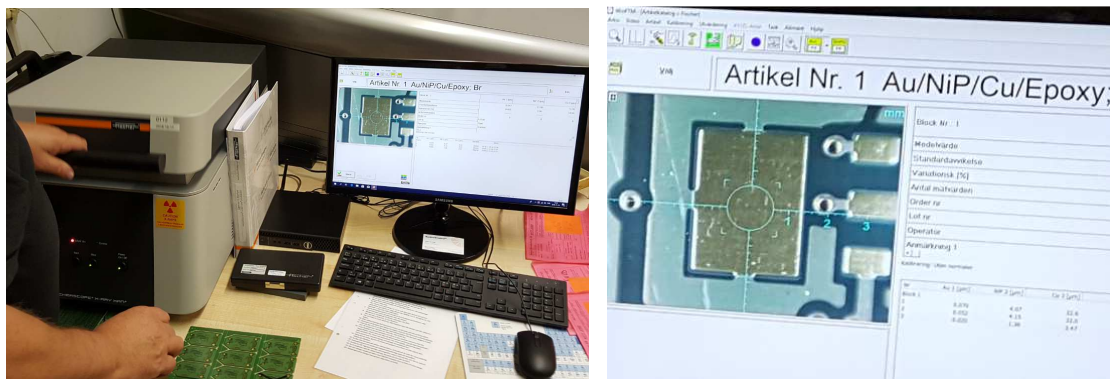


Curt Östh from Atotech instructs Roger Westin and Per-Olof Javermark. There are a lot of parameters to control.



Measurement of Gold by using X-ray

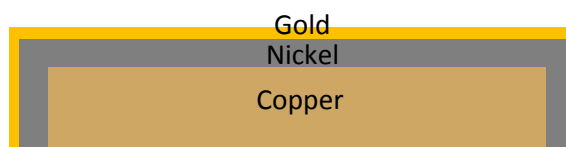
The ENIG process two main steps consists of Nickel and Gold. The nickel layer is required to separate gold from copper. Coating thickness is controlled on each batch by XRF-measurement (X-ray fluorescence) which provides a non destructive measurement result within seconds. The instrument results are compared with the IPC-requirements. The measurements are made with nm-resolution and this large investment makes it possible to measure with higher precision.



Facts about ENIG

ENIG coating are normally made as a selective final finish on all open copper surfaces (pads and vias). Coating are made after soldermask. This means that all conductive tracks are still pure copper.

Properties	
Nickel thickness according to IPC	3 – 6 μm
Gold thickness according to IPC	0,05 – 0,1 μm
Storage conditions	Vacuum package
Shelf life	6-12 months



More information about our products can be found at www.mmab-pcb.com

MMAB Group, Sweden +46 40 64 24 600, sales@mmab-pcb.se

Hungary +36 30 658 22 60, sales.hungary@mmab-pcb.com

Czech Republic +420 601 151 377, sales.czech@mmab-pcb.com

Finland +358 44 320 4588, sales.fi@mmab-pcb.com